

In re Patent Application of:  
**CHARLES CARPENTER**  
Serial No. **09/864,918**  
Filing Date: **May 24, 2001**

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1. A method for manufacturing individual surface acoustic wave (SAW) devices, the method comprising the steps of:

forming a unitary array of a material having opposing first and second surfaces and plural spaced cavities extending into the array from the first surface, each cavity dimensioned to receive a SAW die therein;

forming a recess at each cavity from the first surface, each recess dimensioned to receive a lid within the recess;

providing at least two conductive paths from the interior of each cavity to a surface of the array;

inserting and attaching a SAW die face down into each of a plurality of the cavities, each SAW die having conductive means electrically contacting the conductive paths within the interior of the corresponding cavity after insertion;

sealing a lid in the recess over each inserted SAW die; and then

separating the array into individual SAW devices along separation lines between adjacent cavities.

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6. The method recited in Claim 1, wherein the lid sealing step comprises the steps of:

placing a lid over each cavity;

placing a sealing material about the periphery of each lid; and then

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treating the package array-lids combination so as to seal each lid with the sealing material.

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11. The method recited in Claim 1, further comprising the steps of:

placing a continuous tape across the first surface and the sealed lids prior to the separating step;

undertaking the separating step from the second surface while maintaining continuity of the tape across the first surface; and then removing the individual components from the tape.

12. The method recited in Claim 1, further comprising the step of forming the unitary array from a non-conductive material.

13. The method recited in Claim 12, wherein the unitary array comprises a ceramic.

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15. The method recited in Claim 1, wherein the lid sealing step comprises the step of hermetically sealing the cavity from an ambient environment.

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19. An assembly for manufacturing individual surface acoustic wave (SAW) devices comprising:

a unitary array of a nonconductive material having opposing first and second surfaces and plural spaced cavities extending into the array from the first surface, a plurality of the cavities having a SAW die inserted therein;

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a recess at each cavity extending from the first surface, each recess dimensioned to receive a lid within the recess;

means providing at least two electrically conductive paths from the SAW die within each cavity to an outer surface of the array;

a lid sealed in each recess over an inserted SAW die and the corresponding cavity; and

wherein the array may be separated into individual SAW devices along separation lines between adjacent cavities.

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*Ind B1* **Remarks**

Original Claims 3-5, 14, and 16-18 have been cancelled.

Claims 1-4, 6-15, 19, and 20 remain in the case.

No new matter has been added by this amendment.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version With Markings to Show Changes Made.**"